

RoHS

COMPLIANT HALOGEN

FREE

SSF2300B-VB Datasheet

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^e	Q _g (Typ.)			
	0.028 at V _{GS} = 4.5 V	6 ^a				
20	20 0.042 at V_{GS} = 2.5 V		8.8 nC			
	0.050 at V _{GS} = 1.8 V	5.6				

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- DC/DC Converters
- Load Switch for Portable Applications

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 12		
	T _C = 25 °C		6 ^a		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C		5.1		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _A = 25 °C		5 ^{b, c}		
	T _A = 70 °C		4 ^{b, c}	A	
Pulsed Drain Current		I _{DM} 20	20		
Continuous Source-Drain Diode Current	T _C = 25 °C		1.75		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.04 ^{b, c}		
	T _C = 25 °C		2.1		
Movimum Dower Dissinction	T _C = 70 °C		1.3	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.25 ^{b, c}	vv	
	T _A = 70 °C		0.8 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Tempera		260			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	80	100	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	60	0/10		

Notes:

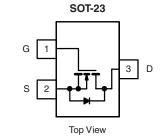
a. Package limited

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 125 °C/W.

e. Based on T_C = 25 °C.



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				.,,,,,			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050 A		25		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 2.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.45		1.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
		$V_{DS} = 20 V, V_{GS} = 0 V$			1	<u> </u>	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 70 °C$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5$ V, V_{GS} = 4.5 V	20			Α	
	. ,	$V_{GS} = 4.5 \text{ V}, I_{D} = 5.0 \text{ A}$		0.028			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 4.7 \text{ A}$		0.042		Ω	
		$V_{GS} = 1.8 \text{ V}, I_D = 4.3 \text{ A}$		0.050			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5.0 A		24		S	
Dynamic ^b						1	
Input Capacitance	C _{iss}		[865		pF	
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		105			
Reverse Transfer Capacitance	C _{rss}			55			
		$V_{DS} = 10 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 5.0 \text{ A}$		12	18	-	
Total Gate Charge	Qg			8.8	14	- nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5.0 \text{ A}$		1.1			
Gate-Drain Charge	Q _{gd}			0.7			
Gate Resistance	Rg	f = 1 MHz	0.5	2.4	4.8	Ω	
Turn-On Delay Time	t _{d(on)}			8	16	-	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		17	26		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong \text{4}$ A, V_GEN = 4.5 V, R_g = 1 Ω		31	47		
Fall Time	t _f			8	16	ns	
Turn-On Delay Time	t _{d(on)}			5	10	113	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		13	20	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 4 \text{ A}, V_{GEN} = 5 \text{ V}, R_g = 1 \Omega$		21	32		
Fall Time	t _f			6	12		
Drain-Source Body Diode Characteristic	cs		Į			<u>I</u>	
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			1.75		
Pulse Diode Forward Current	I _{SM}				20	A	
Body Diode Voltage	V _{SD}	$I_{S} = 4 A, V_{GS} = 0 V$		0.75	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			12	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			5	10	nC	
Reverse Recovery Fall Time	t _a	$I_F = 4 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$		7			
Reverse Recovery Rise Time	t _b			5		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



- 55 °C

1.5

20

T_C =

1.2

0.9

10

Capacitance

25

50

75

 $V_{GS} = 2.5 \text{ V}, I_D = 4.7 \text{ A}$

15

 $V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$

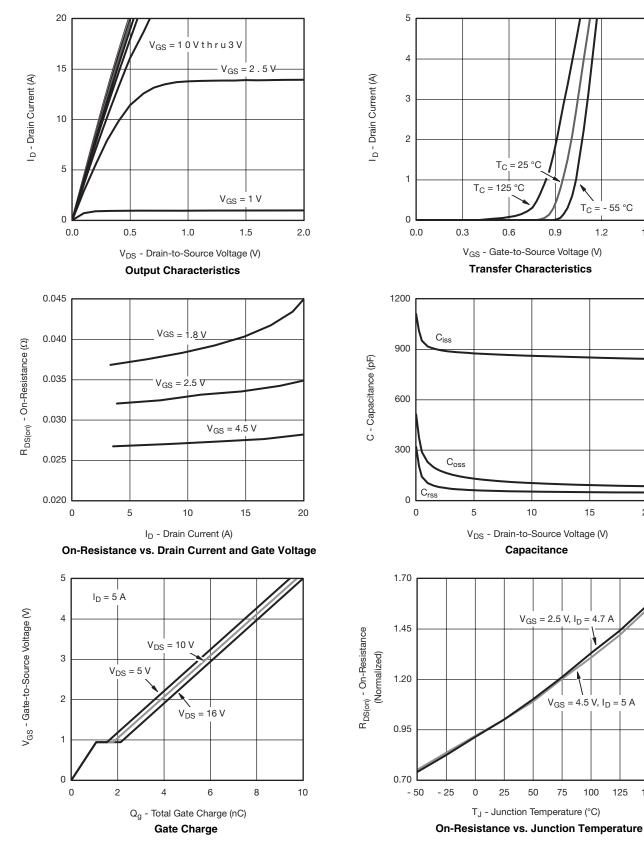
100

125 150

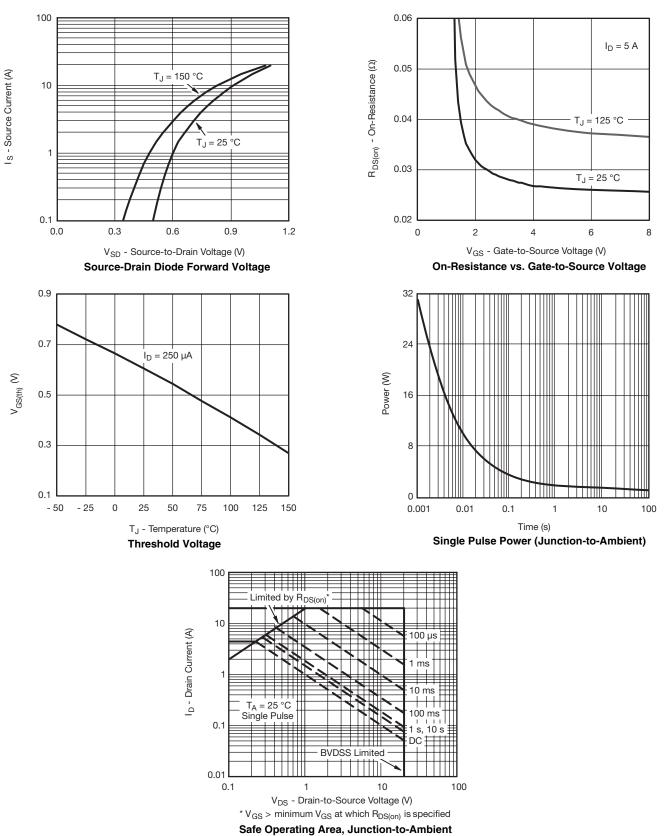
T_C = 25 °C

0.6

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







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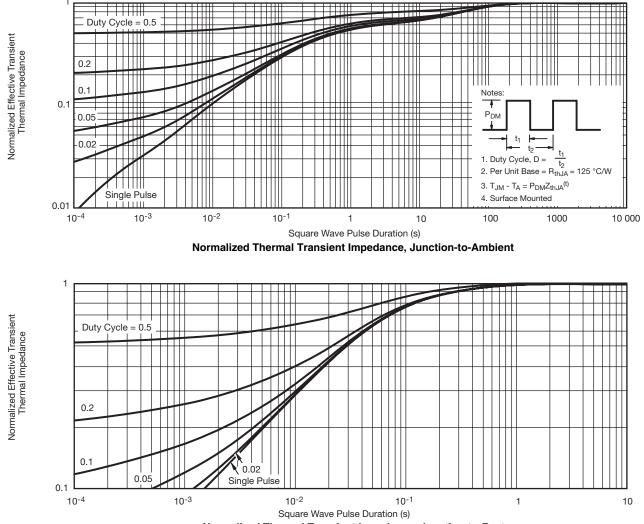
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



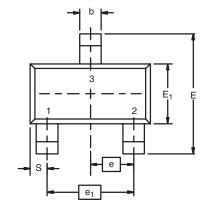
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



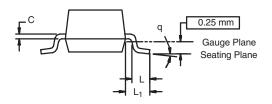
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD



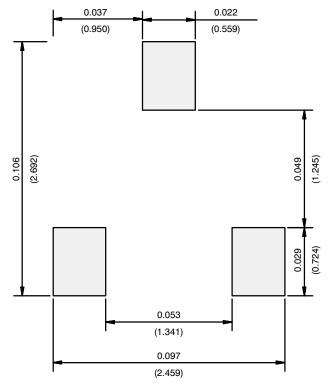




Dim -	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K, 09-J DWG: 5479	ul-01	•			



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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